

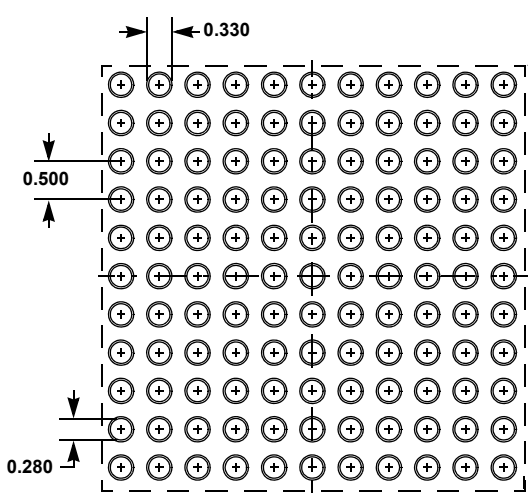
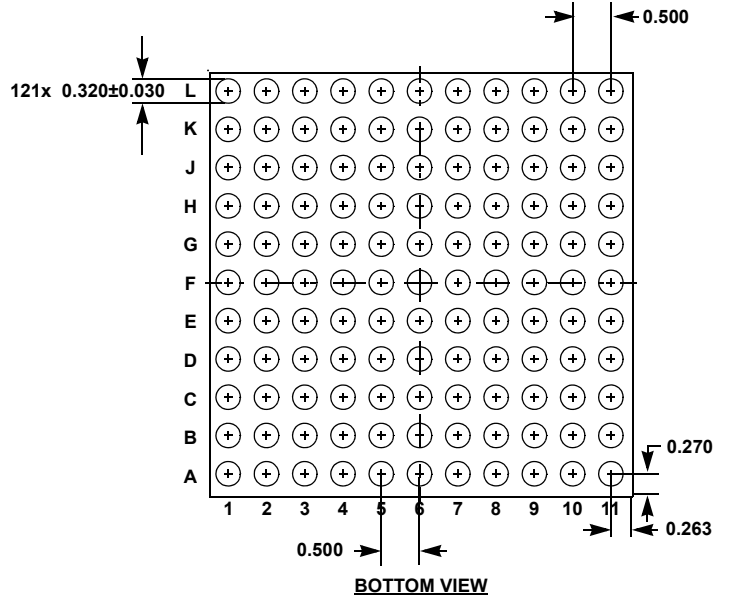
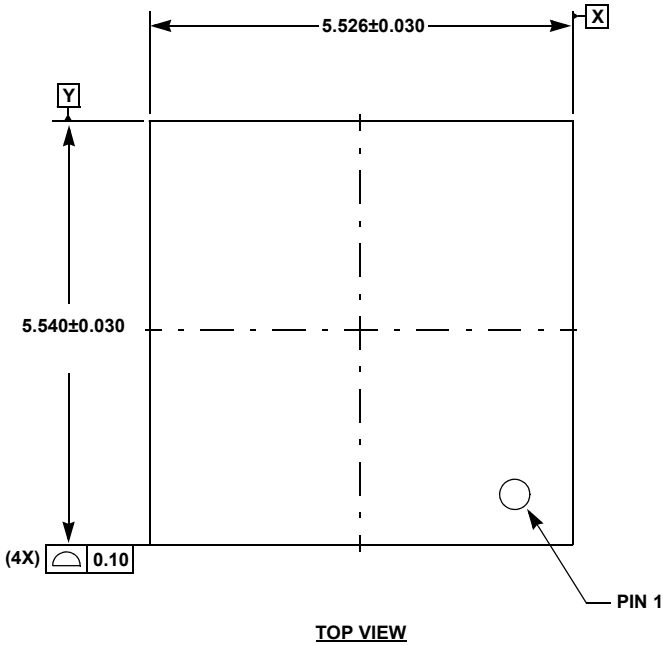
Plastic Packages for Integrated Circuits

Package Outline Drawing

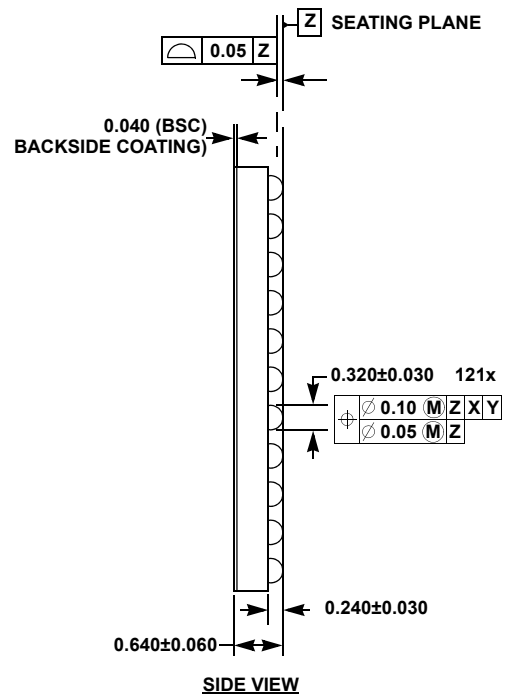
W11x11.121A

121 BALL WAFER LEVEL CHIP SCALE PACKAGE (WLCSP 0.5mm pitch) (BSC)

Rev 1, 2/14



3 NSMD
TYPICAL RECOMMENDED LAND PATTERN



NOTES:

1. All dimensions are in millimeters.
 2. Dimensions and tolerance per ASMEY 14.5M - 1994 and JESD 95-1, SPP-010.
- 3 NSMD refers to non-solder mask defined pad design per Intersil Techbrief [TB451](#).